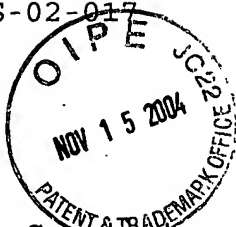


IFW

APS-02-017



November 4, 2004

To: Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Attn: Art Unit 2811 - Quang D. Vu

From: George O. Saile, Reg. No. 19,572

28 Davis Avenue

Poughkeepsie, N. Y., 12603

Subject: | Serial No.: 10/690,996 10/22/03 |

Tan Kim Hwee et al.

FLIP CHIP PACKAGE USING NO-FLOW  
UNDERFILL AND METHOD OF FABRICATION

| \_ Art Group: 2811 Quang D. Vu \_ |

RESPONSE TO RESTRICTION REQUIREMENT

This is in response to the Restriction or Election Requirement in the Office Action dated 10/22/04. In that Office Action, restriction was required to one of two stated

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 12, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 11/12/04

Inventions under 35 U.S.C. 121. The Inventions stated are Group I - Claims 1-12 to a semiconductor package, classified in Class 257, subclass 778 and Group II - Claims 13-15 to a process, classified in Class 438, subclass 108.

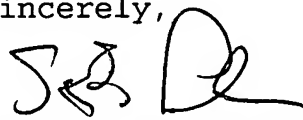
Applicant provisionally elects to be examined the Invention described by the Examiner as Group II - Claims 13-15 drawn to a process classified in Class 438, subclass 108. This election is made with traverse of the requirement under 37 C.F.R.1.143 for the reasons given in the following paragraphs.

The Examiner is respectfully requested to reconsider the Requirement for Restriction given in the Office Action. The Examiner gives the reason for the distinctness of the two inventions as (1) that the process as claimed can be used to make other and materially different products or (2) that the product as claimed can be made by another and materially different process (MPEP 806.05(f)). However, upon reading the product Claims against the process Claims one can readily see that the product Claims are directed to "a semiconductor package" and the process Claims are directed to "a method of fabricating a semiconductor package", it is necessary to obtain claims in both the product and method claim language. The method Claims necessarily use the product and vice versa. The field of search must necessarily cover both the method class/subclass 438/108 and products class 257/778 in addition

to other related Classes and subclasses to provide a complete and adequate search. The fields of search for the Group I and Group II inventions are clearly and necessarily co-extensive. The Examiner's suggestion that "In the instant case the group I invention could be made by a materially different process. For example, positioning the solder bumped semiconductor chip in contact with the surface metallized substrate, and then injecting a no-flow underfill in a space between the semiconductor chip and the surface metallized substrate, instead of disposing a no-flow underfill to the surface metallized substrate and positioning the solder bumped semiconductor chip in contact with the surface metallized substrate", is very speculative and really has nothing to do with the Claims as presented in this Patent Application. Further, it is respectfully suggested that these reasons are insufficient to place the additional cost of a second Patent Application upon the Applicants. Therefore, it is respectfully requested that the Examiner withdraw this restriction requirement for these reasons.

Withdrawal of the Restriction Requirement and the Allowance of the present Patent Application is requested.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', with a large, stylized flourish extending from the end.

Stephen B. Ackerman, Reg. #37761